

Direct Time-of-Flight (dTOF) imaging for depth sensing applications

Augusto Ronchini Ximenes

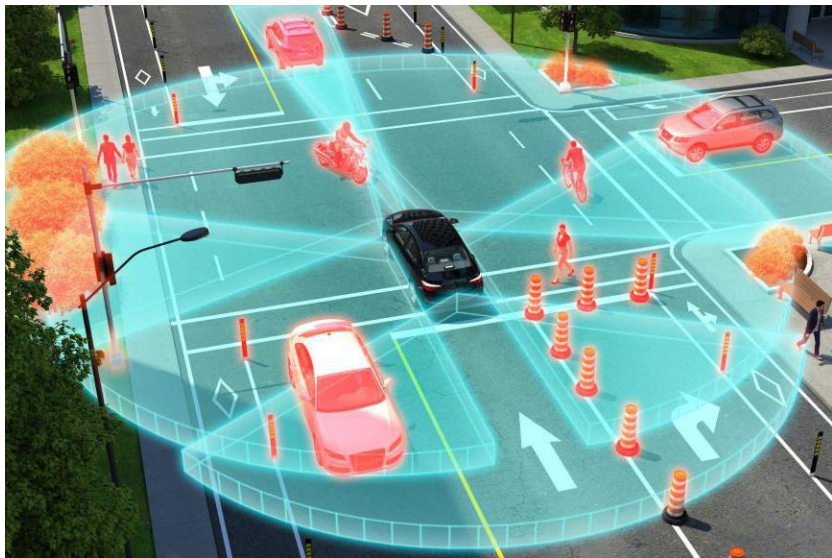
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Agenda

- Applications
- Direct Time-of-Flight (dTOF) operation
- Challenges
- Our approach
- Conclusion

Applications

Advanced driver-assistance systems (ADAS) and autonomous vehicles



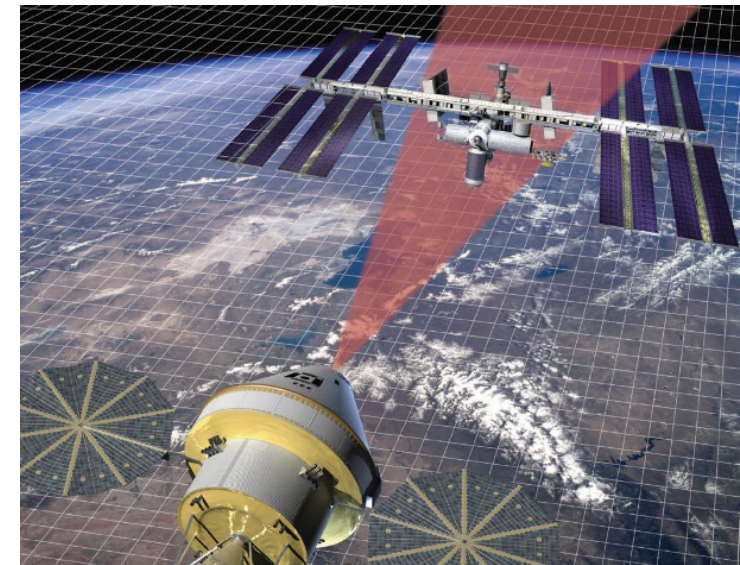
LeddarTech

Face recognition and human-machine interface



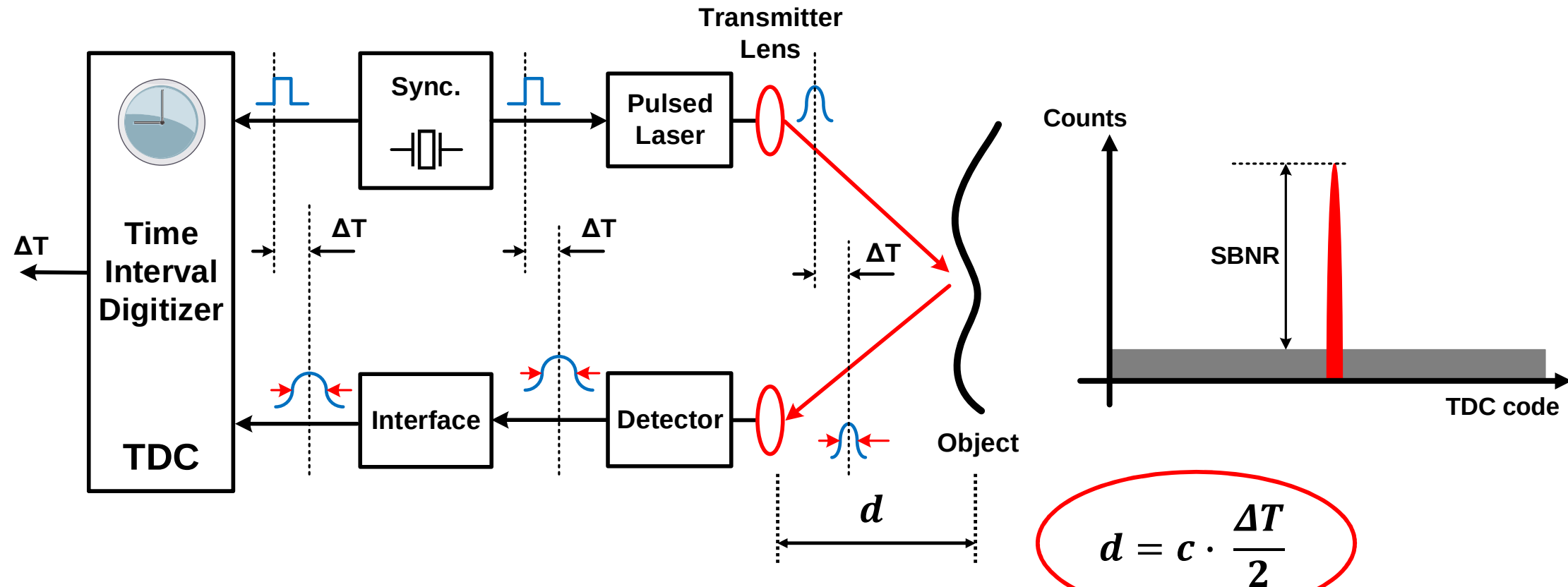
Apple

Spacecraft navigation systems



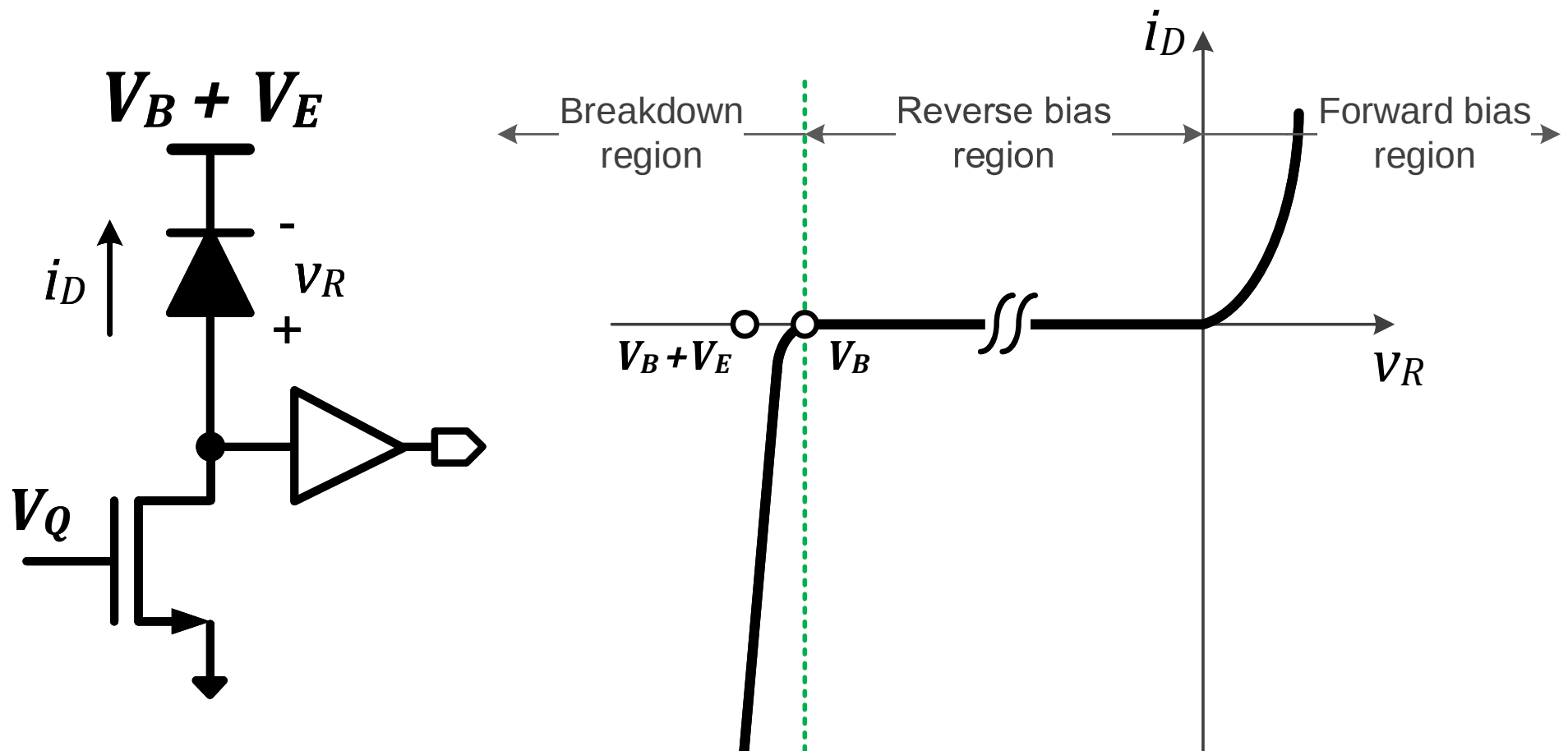
NASA

Direct Time-of-Flight (TCSPC)

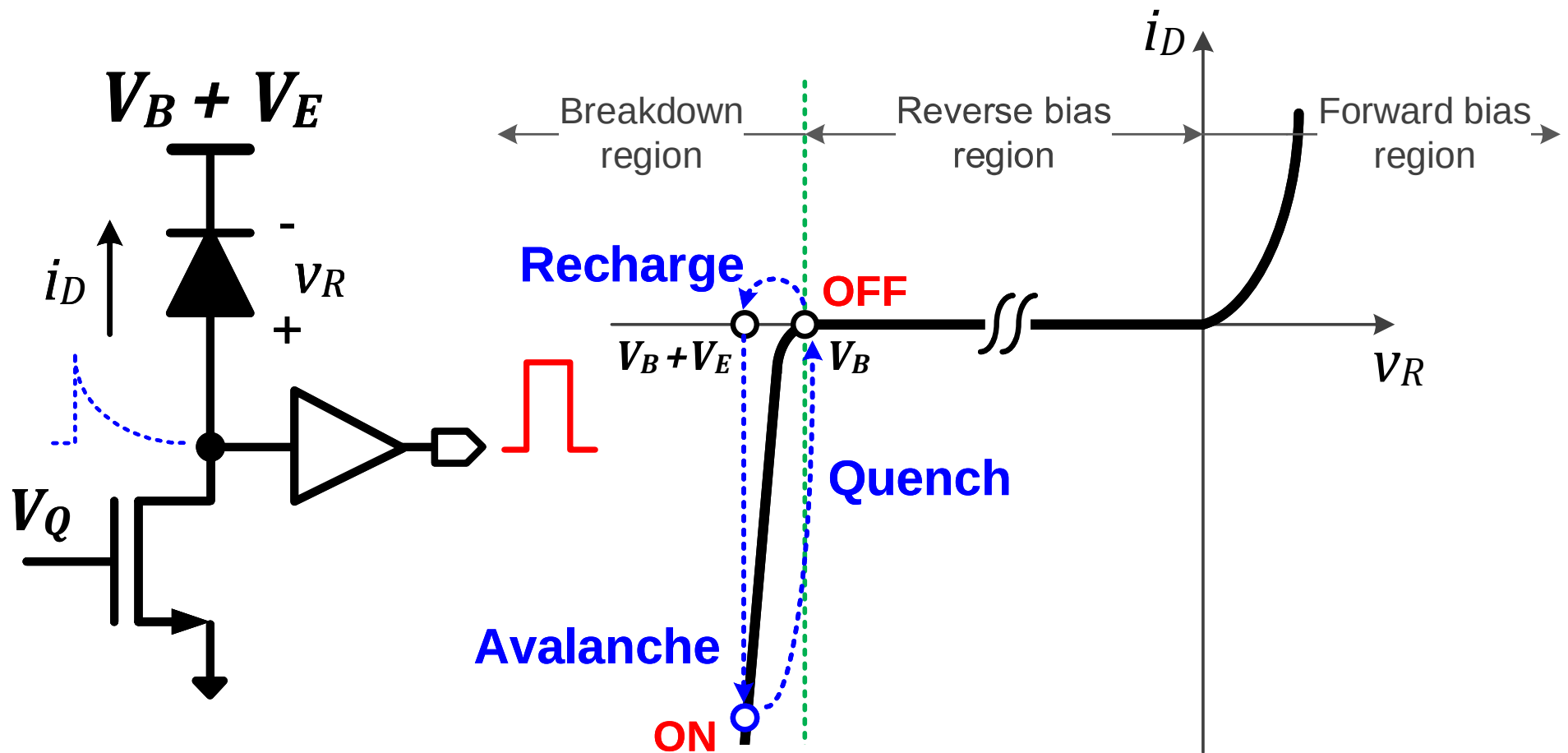


Accurate and fast depth detection

Single-Photon Avalanche Diode Technology

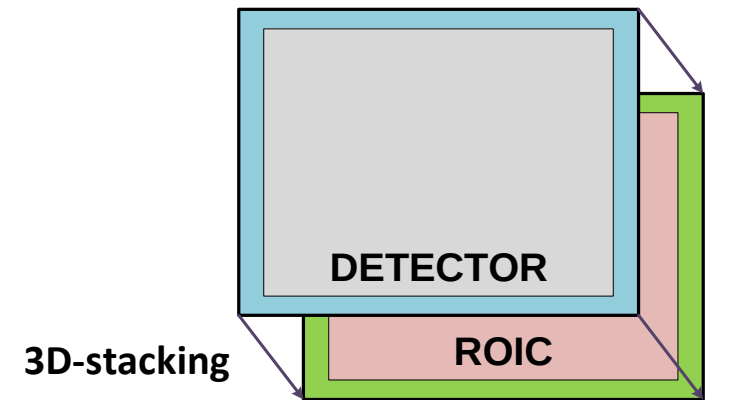
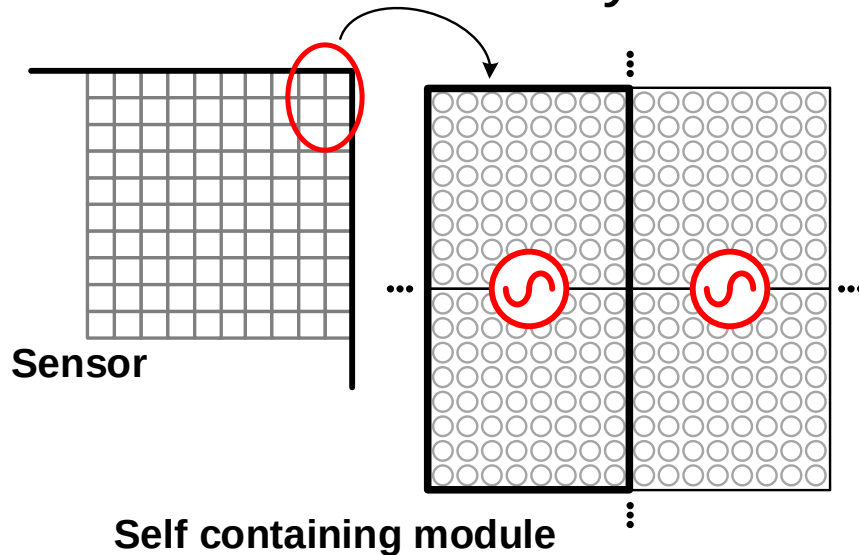


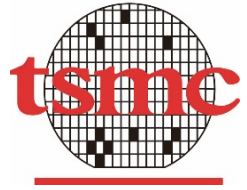
Single-Photon Avalanche Diode Technology



Challenges

- Increase functionality at lower power consumption
- Increase sensitive area
- Precise timing in megapixel arrays
- Robust to wide variety of conditions



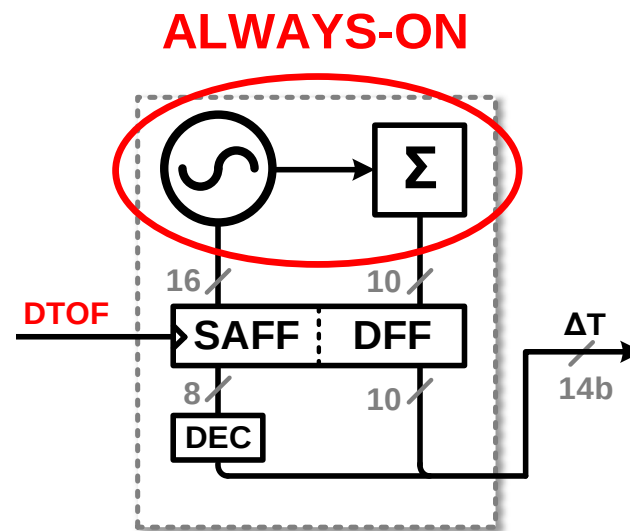


Sensor architecture

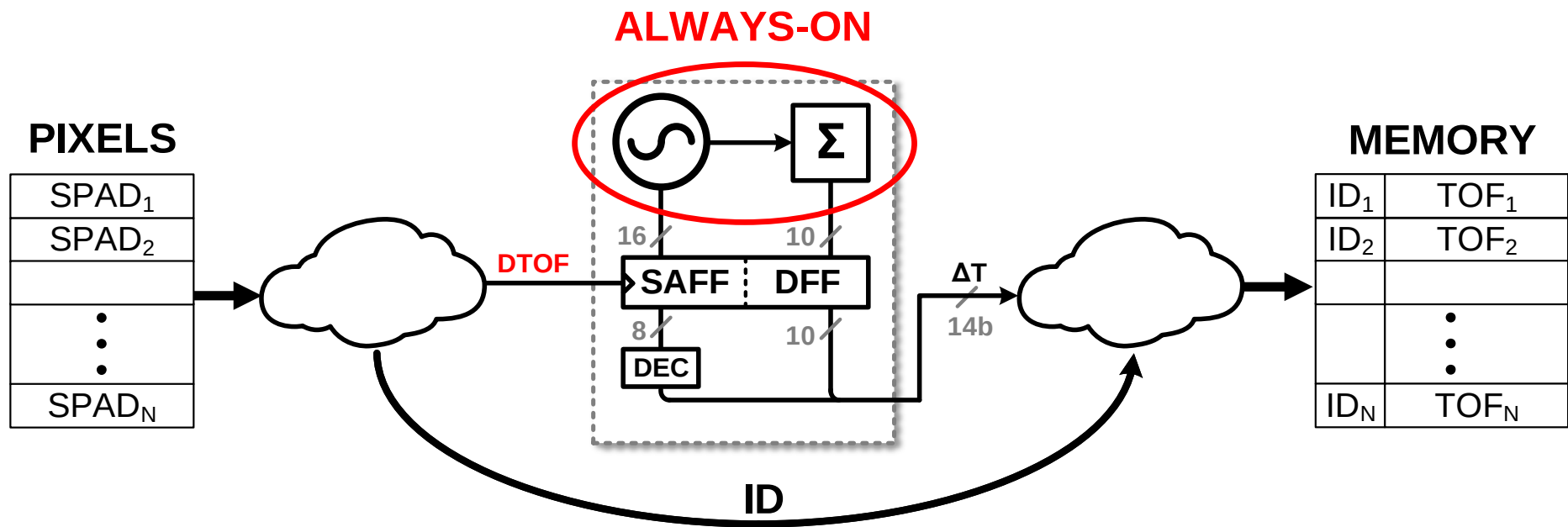
ISSCC 2018: *A 256x256 45/65nm 3D-Stacked SPAD-Based Direct TOF Image Sensor for LiDAR Applications with Optical Polar Modulation for up to 18.6dB Interference Suppression*

A. R. Ximenes¹, P. Padmanabhan², M.-J. Lee², Y. Yamashita³, D. N. Yaung³, E. Charbon^{1,2}

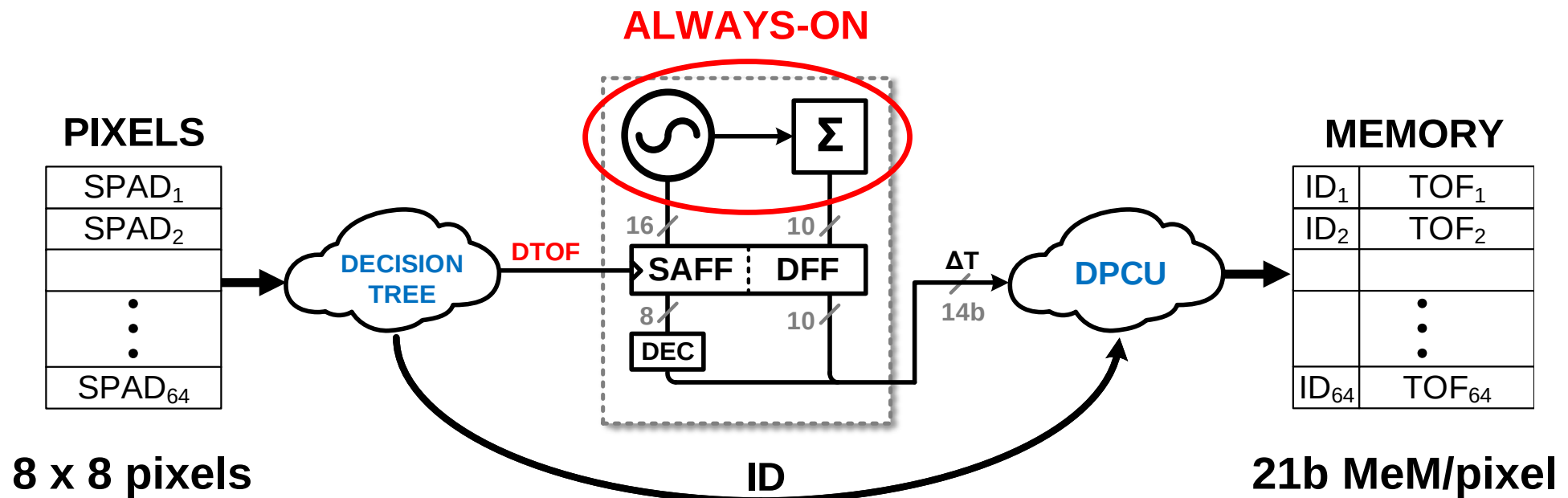
Time-to-Digital Converter (TDC) operation



TDC sharing



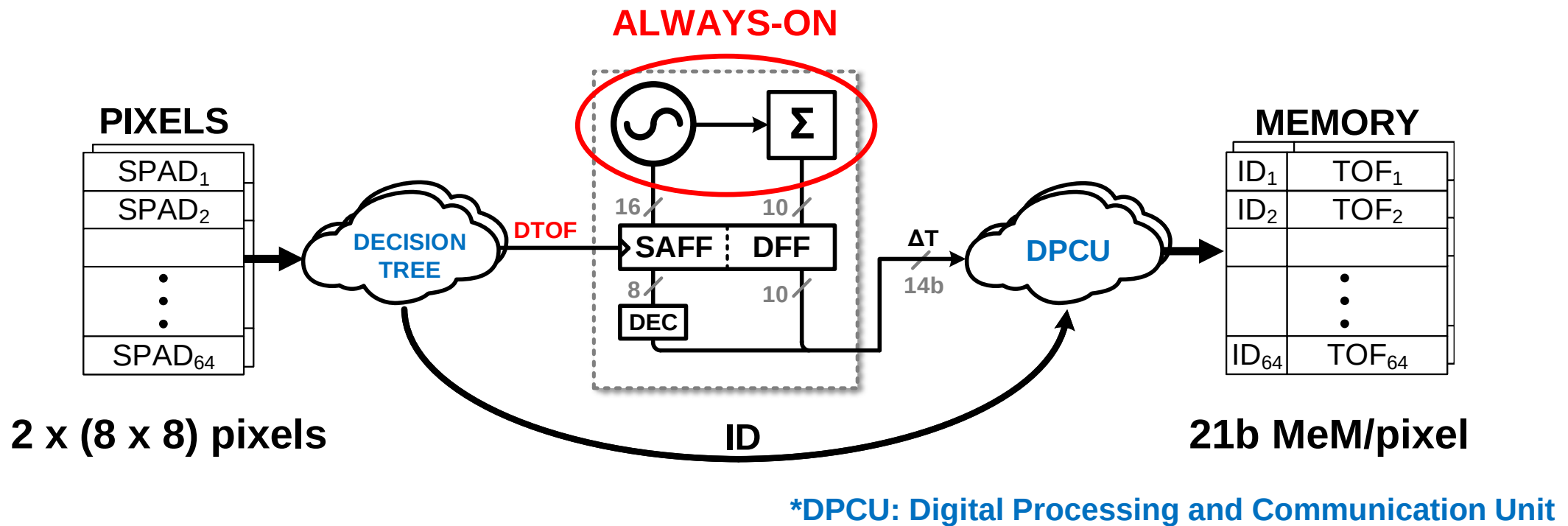
Complete subgroup



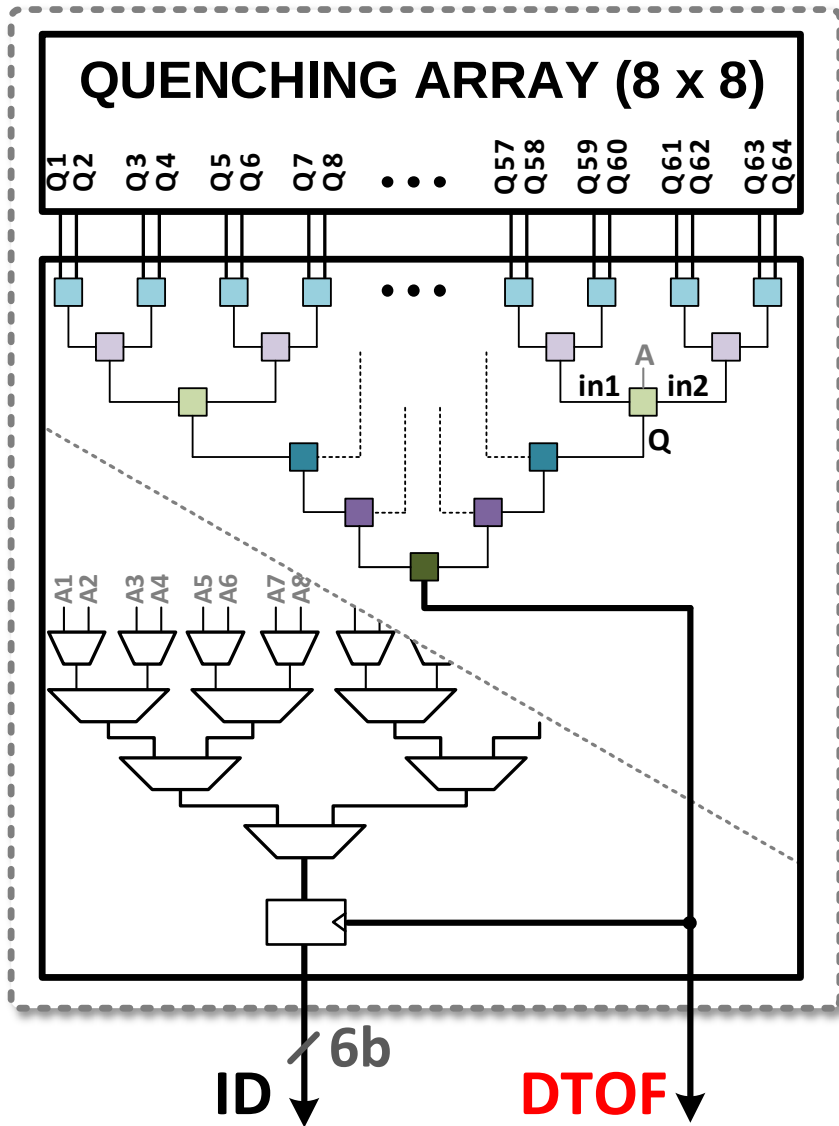
*DPCU: Digital Processing and Communication Unit

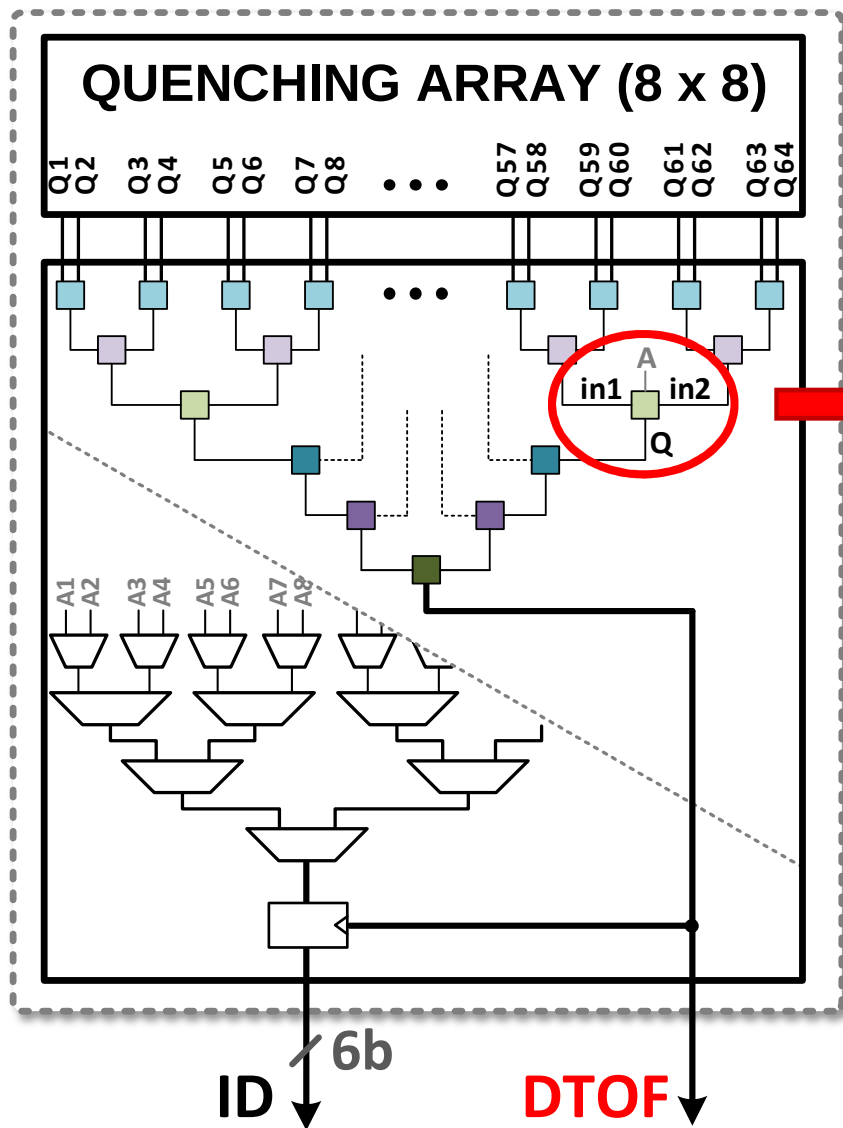
Self-contained module

TDC SHARED AMONG 2 SUBGROUPS

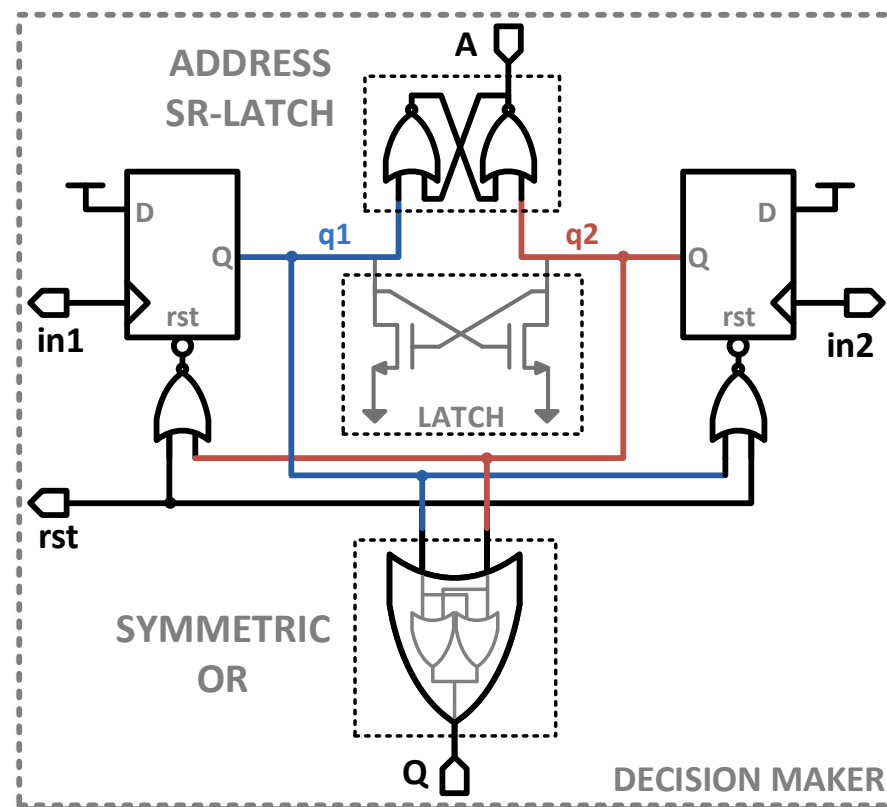


Decision Tree





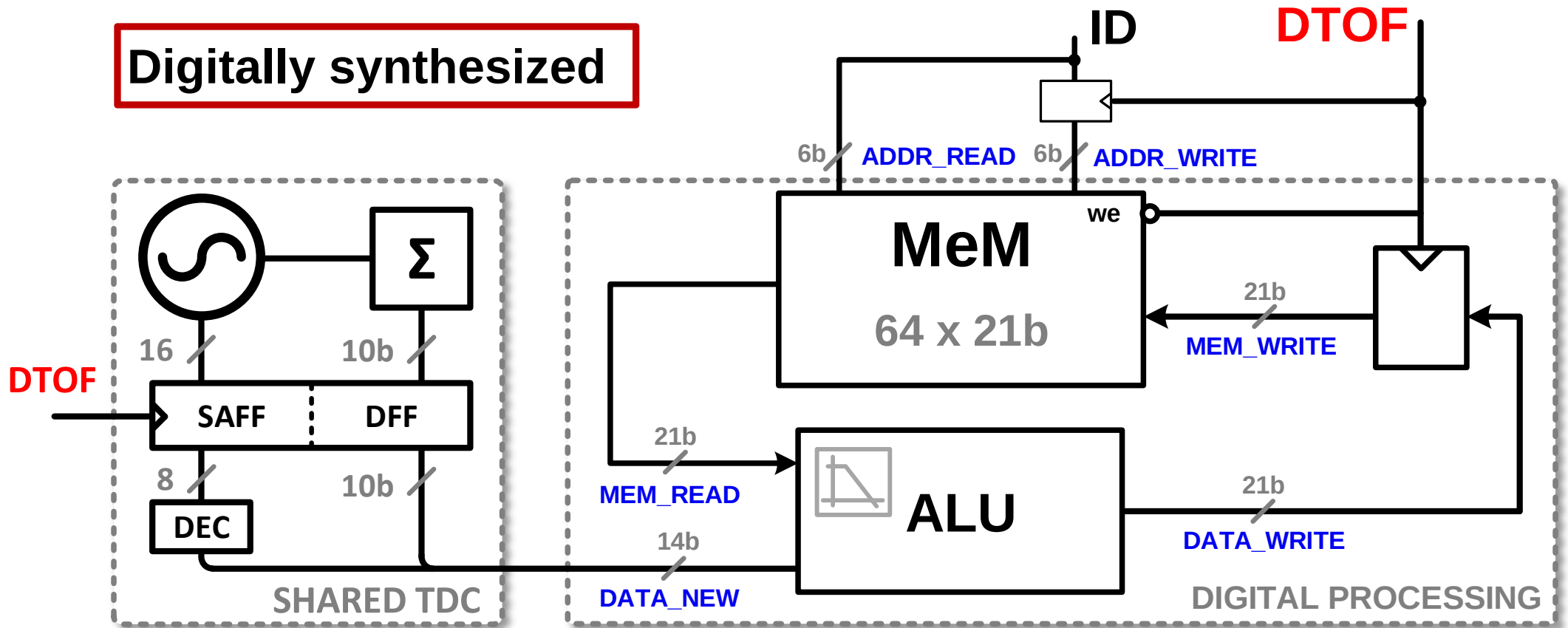
Decision Tree



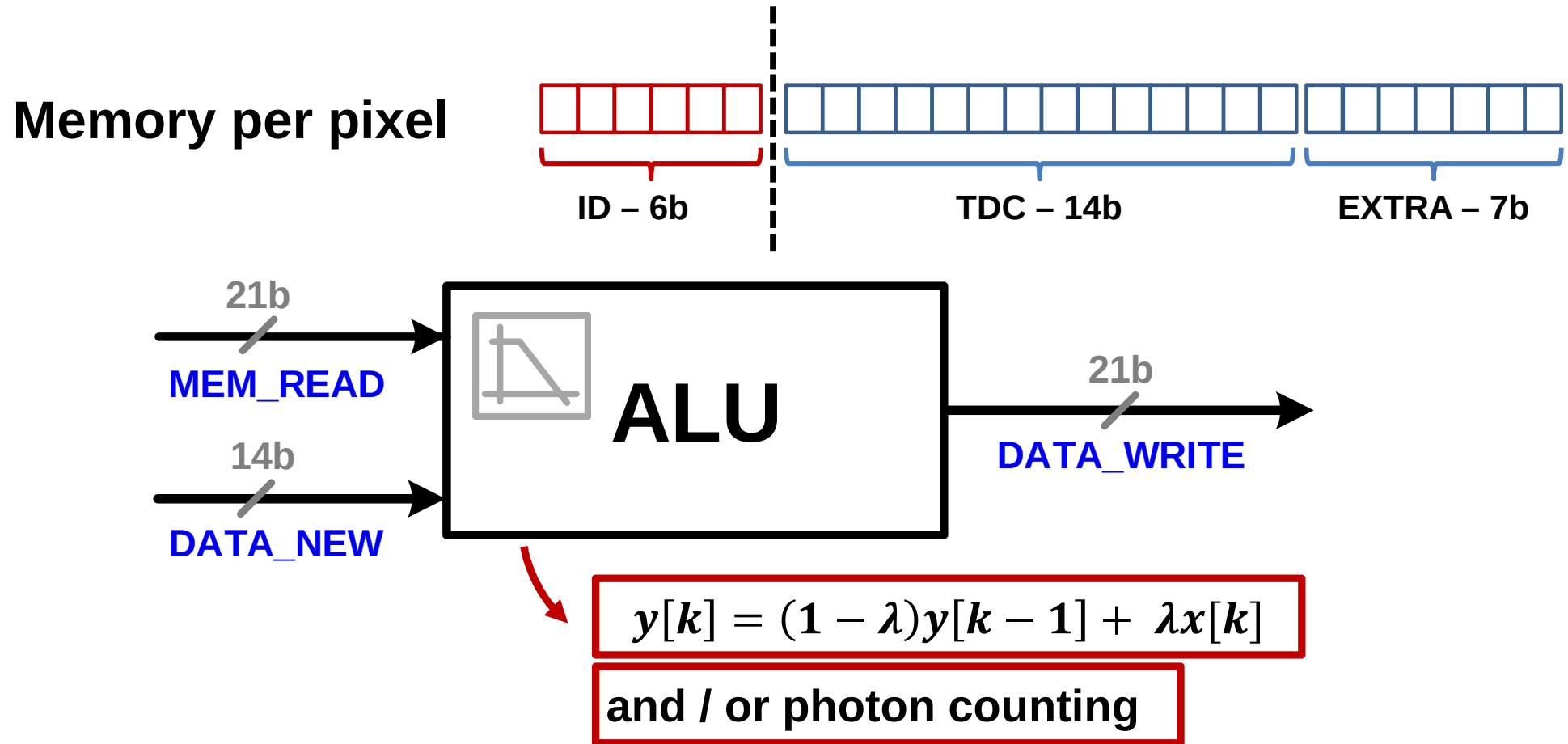
Metastability < 10 ps
Overall tree skew < 14 ps

Digital Processing and Communication Unit

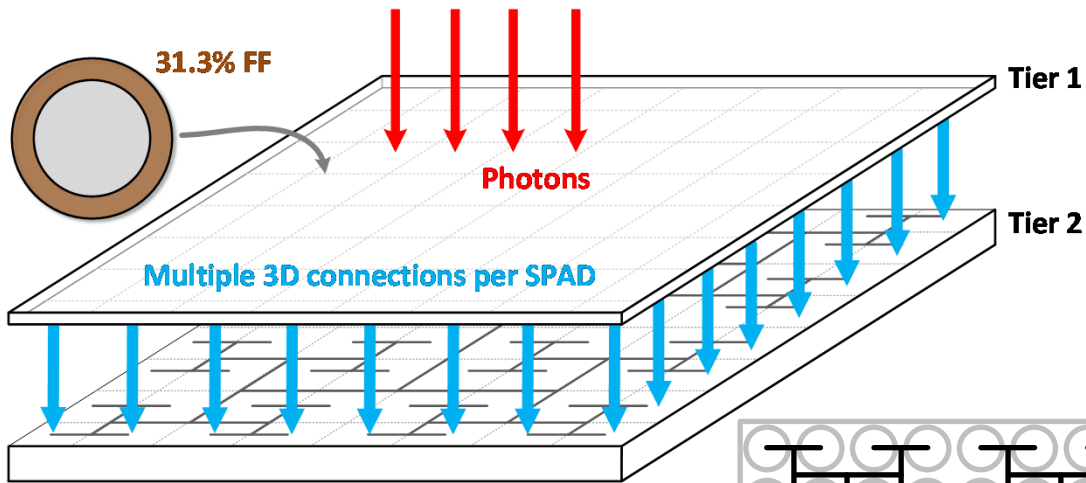
Digitally synthesized



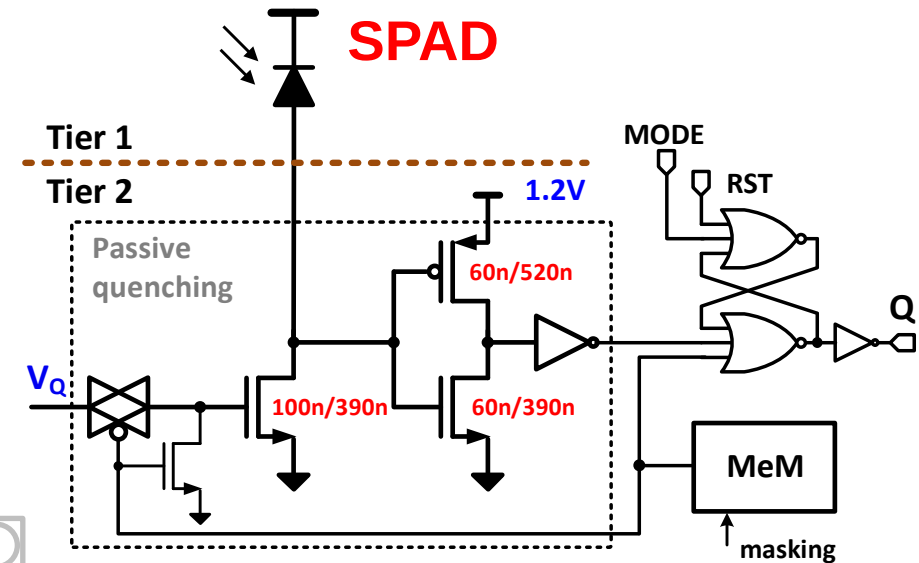
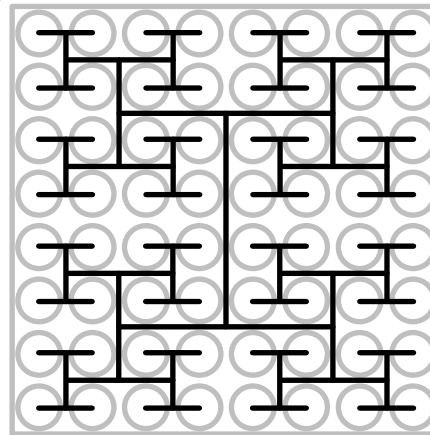
Digital Processing and Communication Unit



3D stacking and modularity



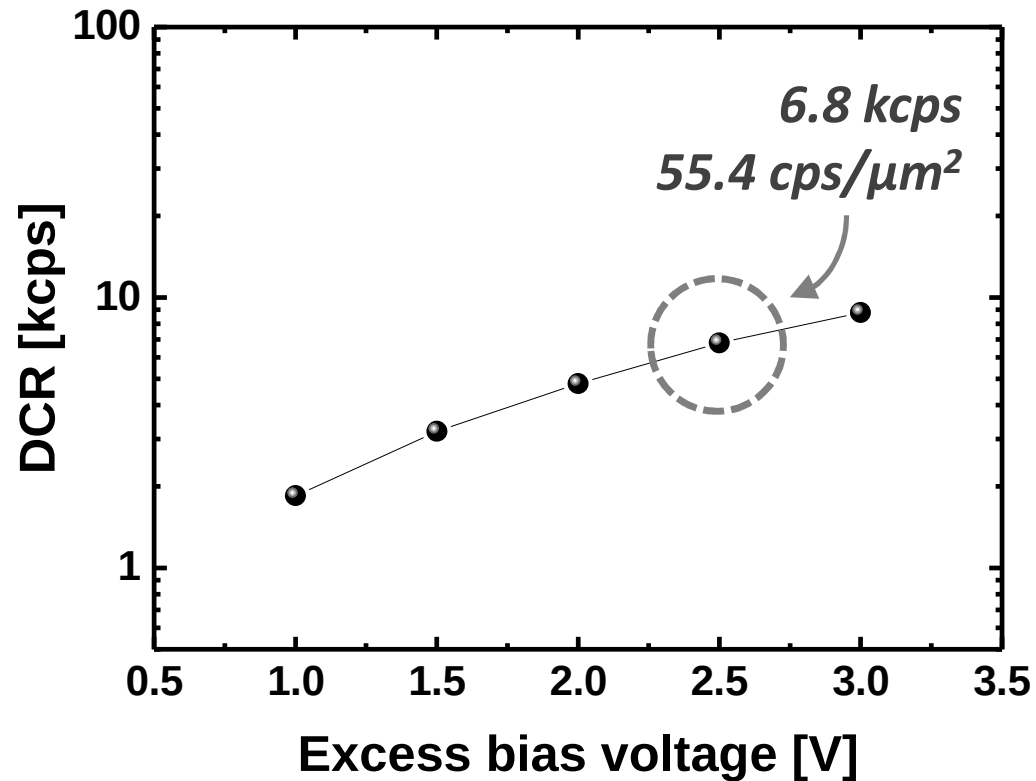
SUBGROUP
8 x 8 SPADs



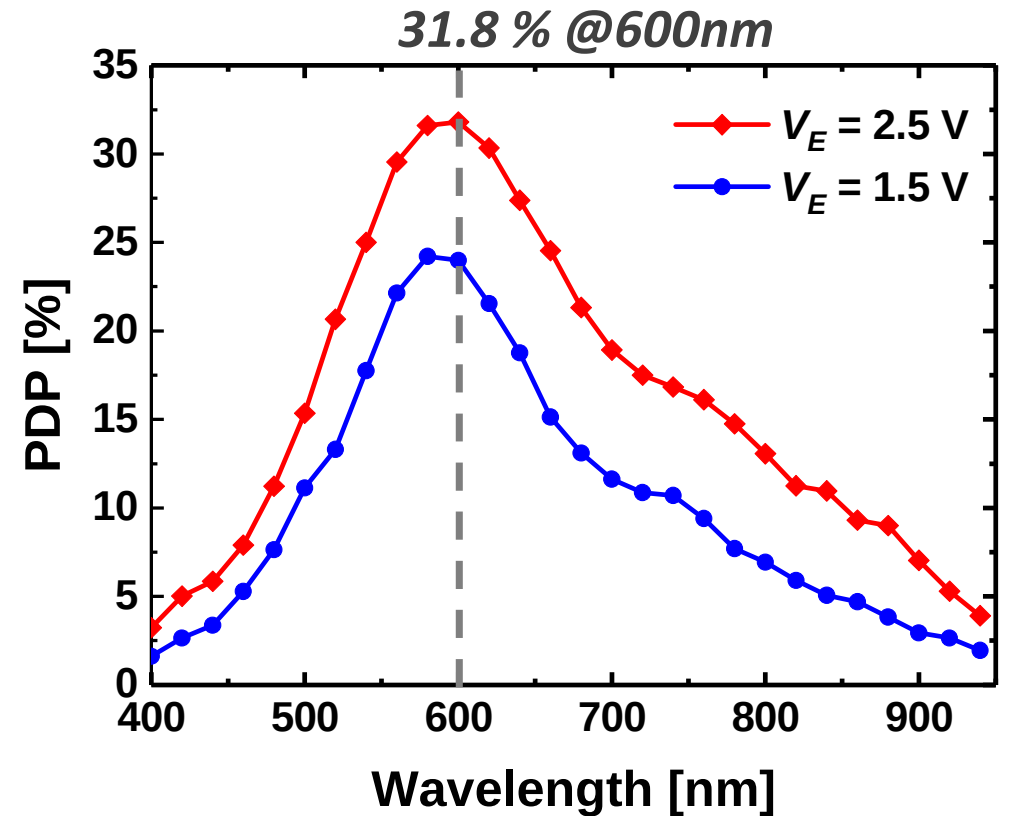
- Passive quenching
- Electrical & optical mask
- Pulse/State output modes
- External Reset

Results

BSI SPAD performance

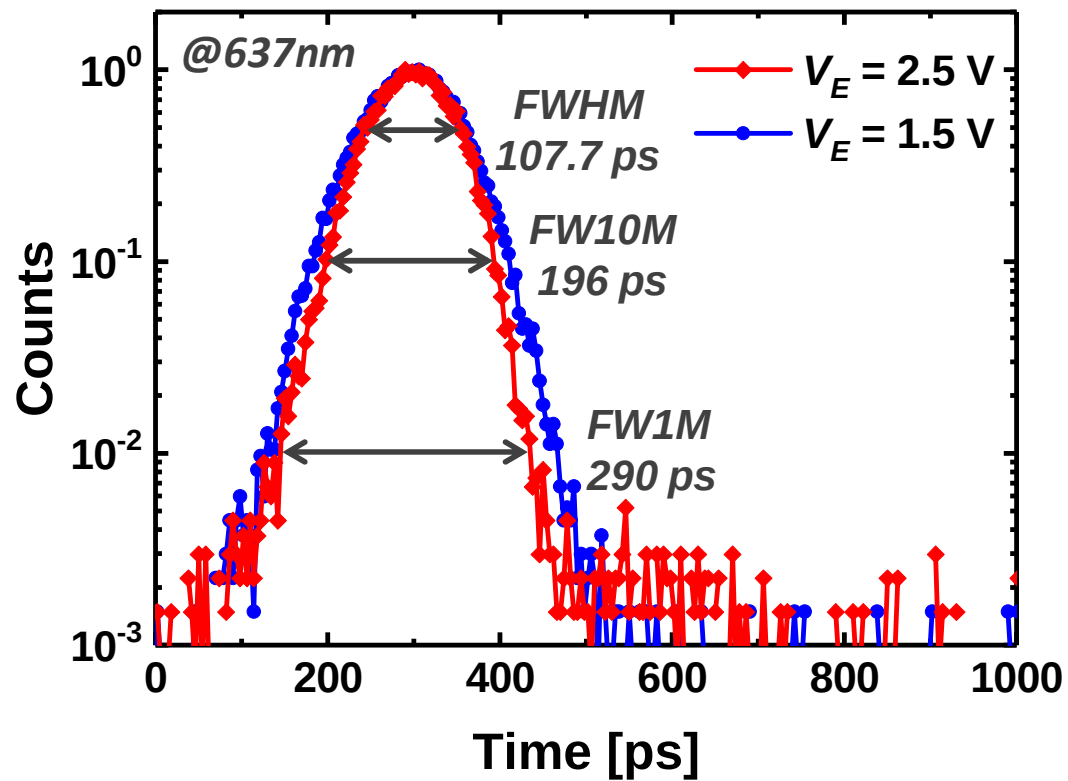


Triggered by any generation of free carriers instead of incident photons

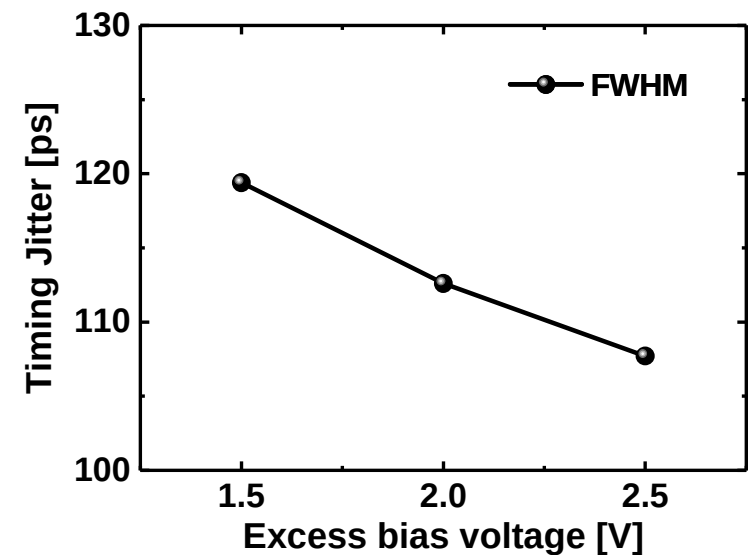
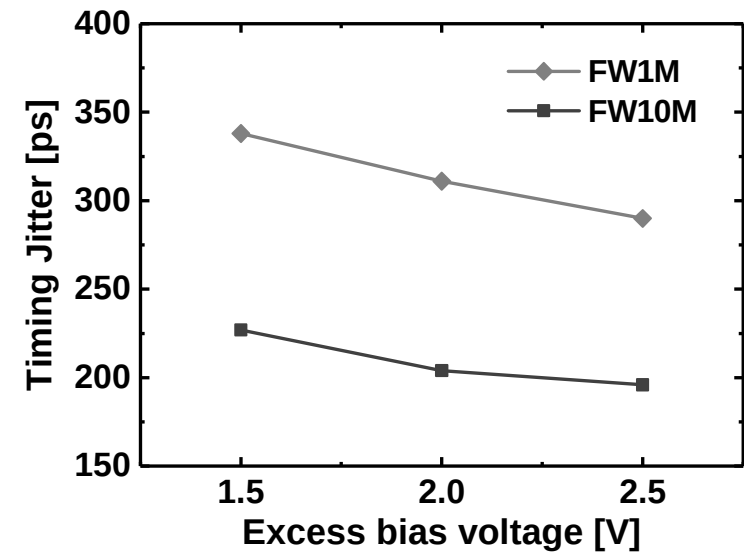


Probability of detection when a photon hits the SPAD's active area

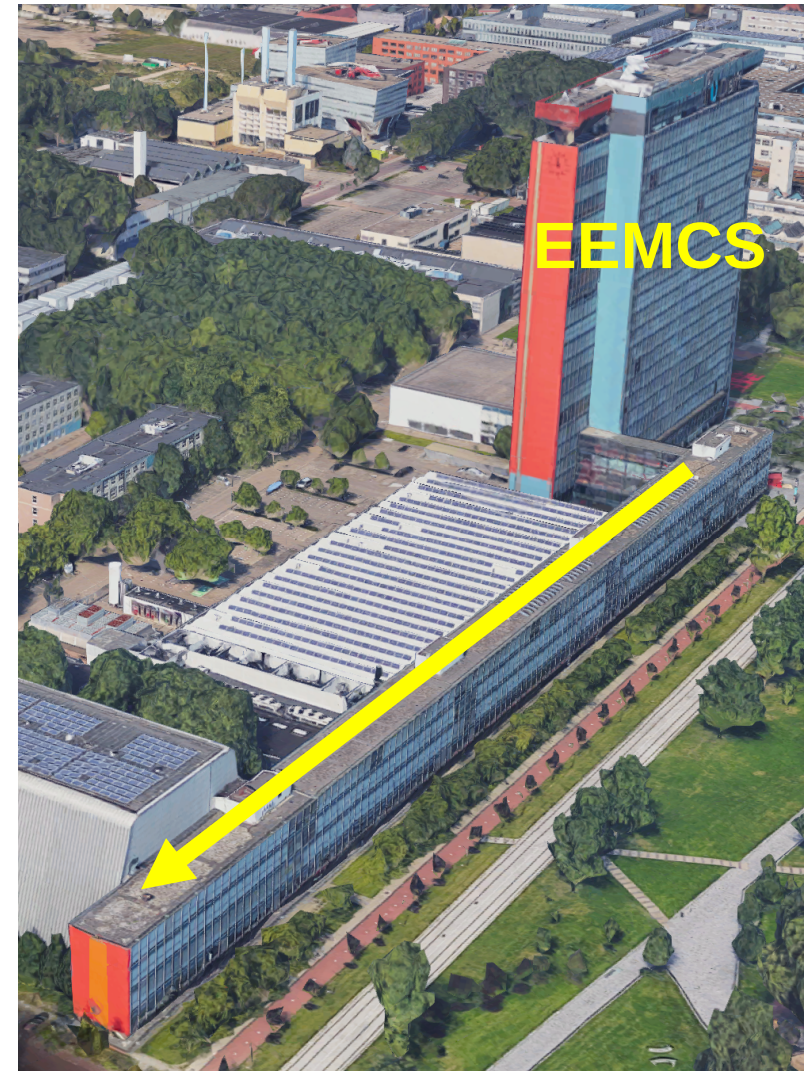
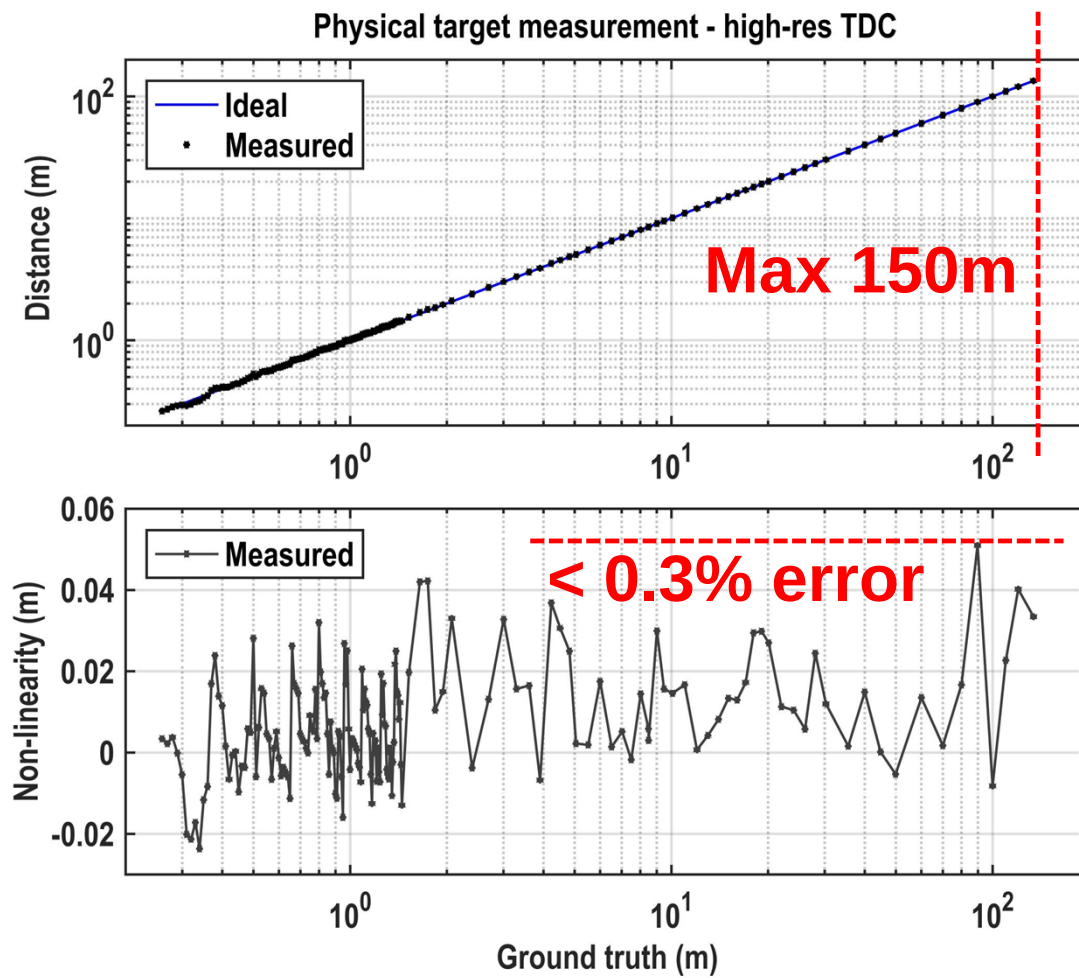
BSI SPAD performance



**IEDM 2017: A Back-Illuminated 3D-Stacked Single-Photon Avalanche Diode in 45nm CMOS Technology, MJ Lee, et. al., TUDELFT, EPFL, TSMC.*

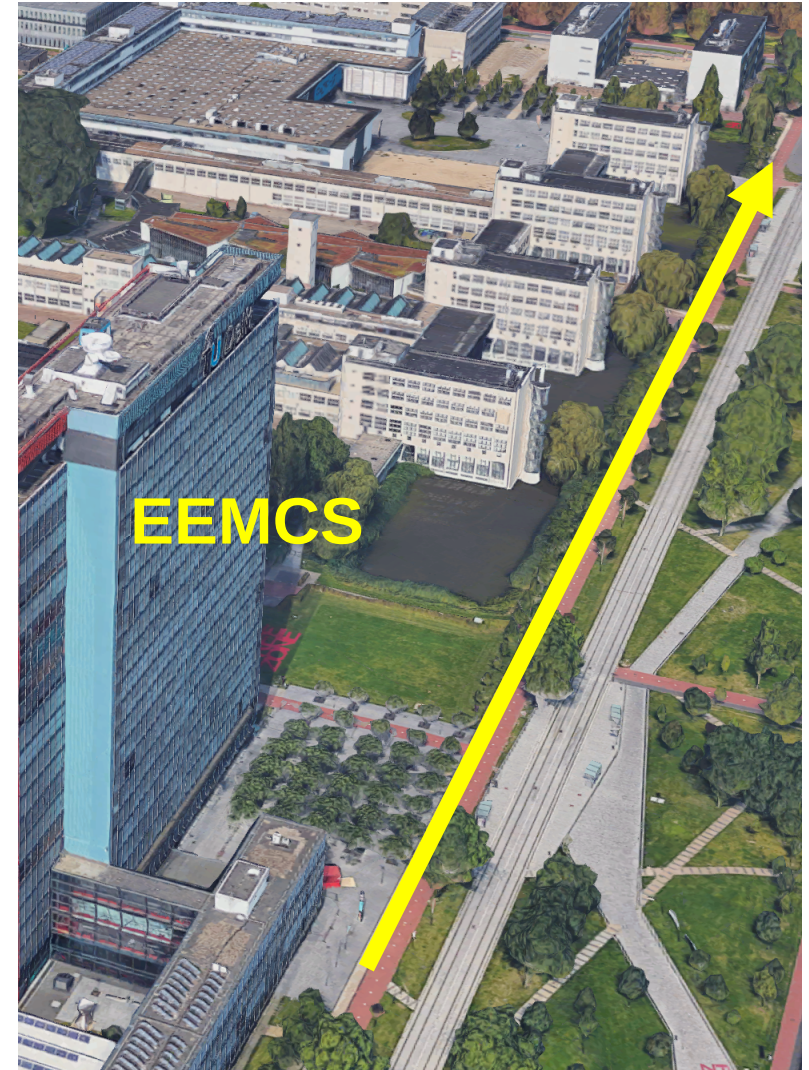
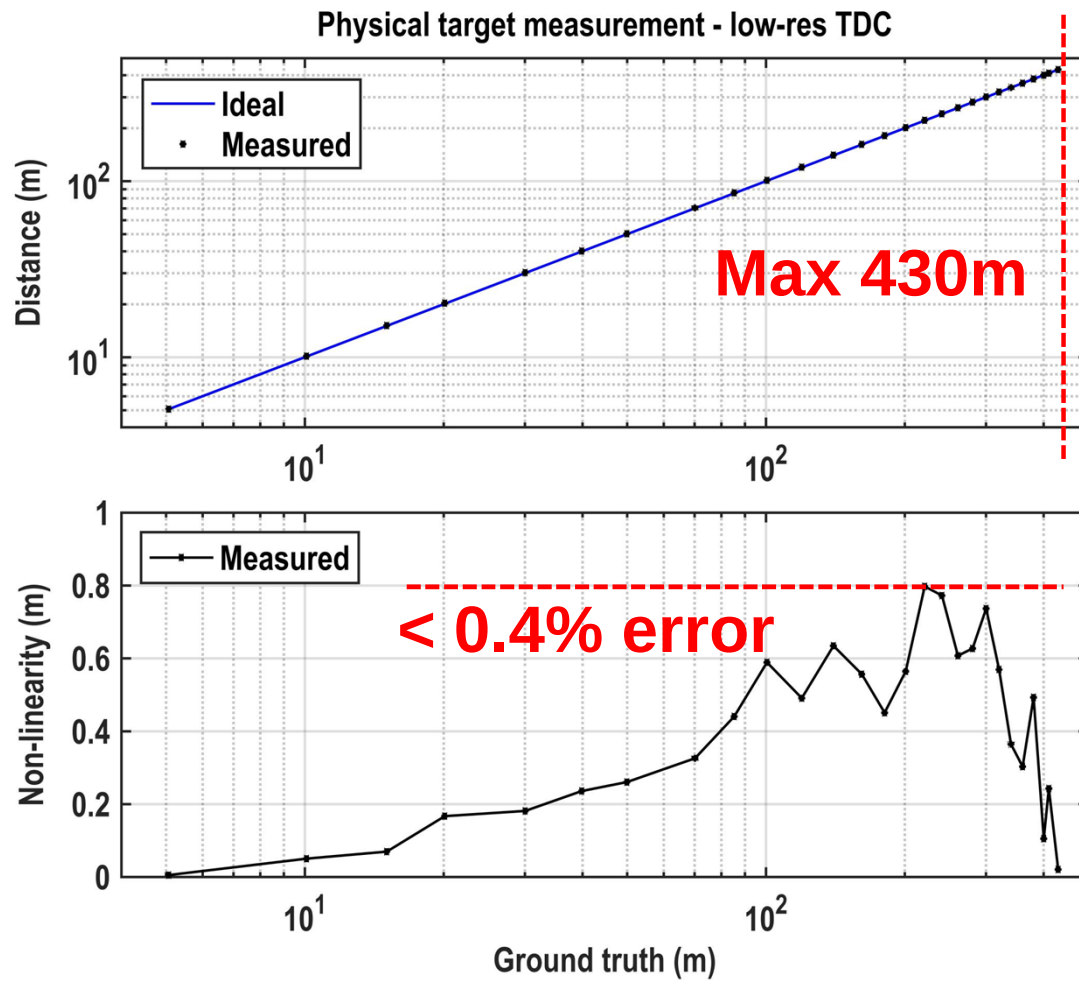


High res TDC



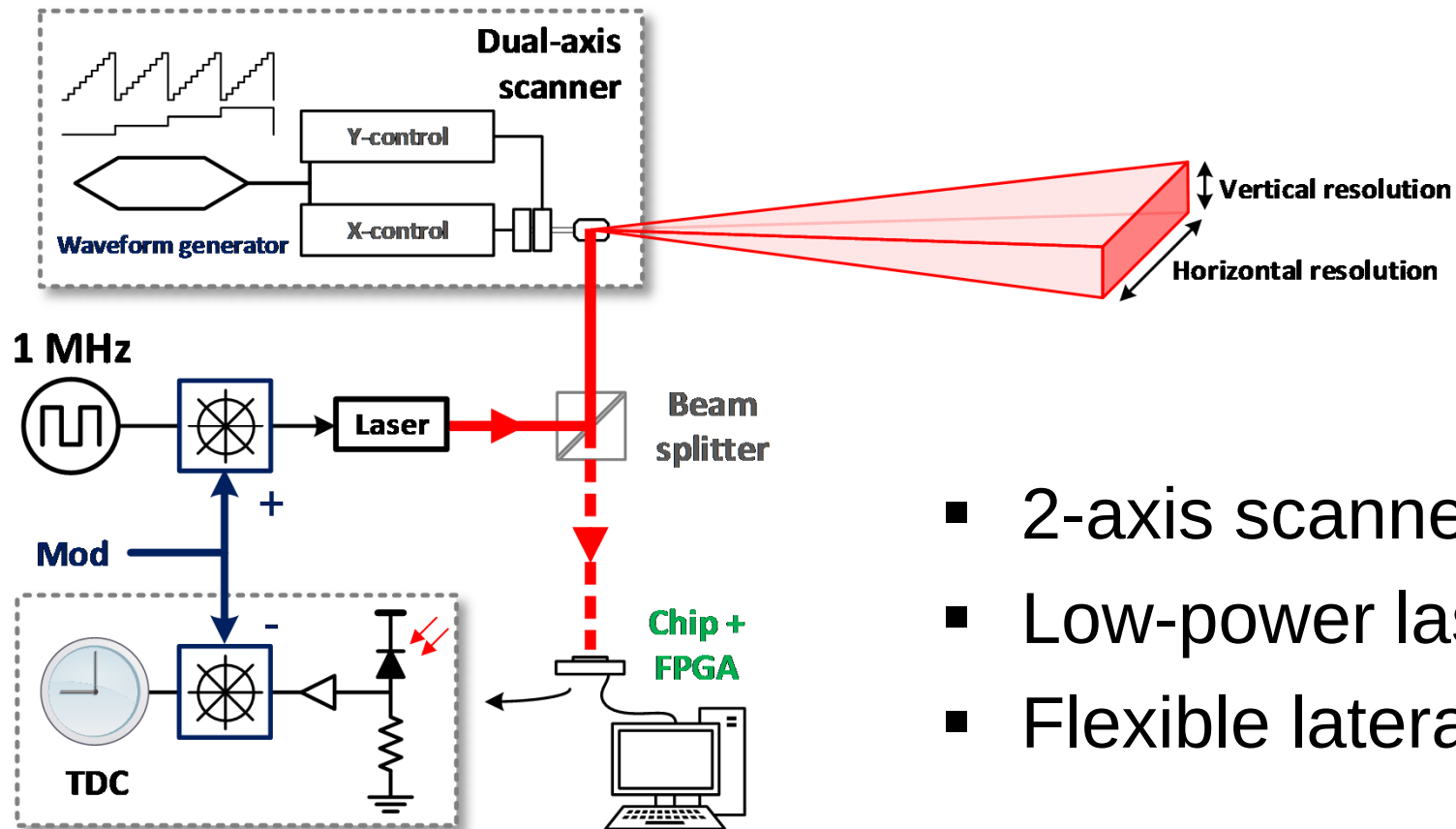
TU Delft campus @ googlemaps

Low res TDC



TU Delft campus @ googlemaps

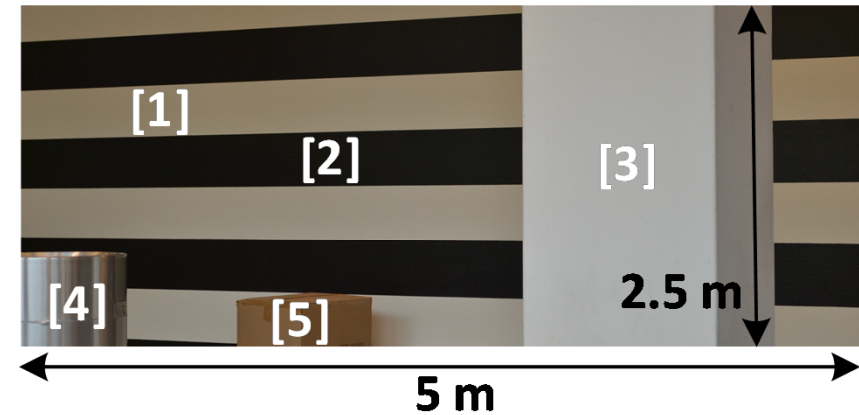
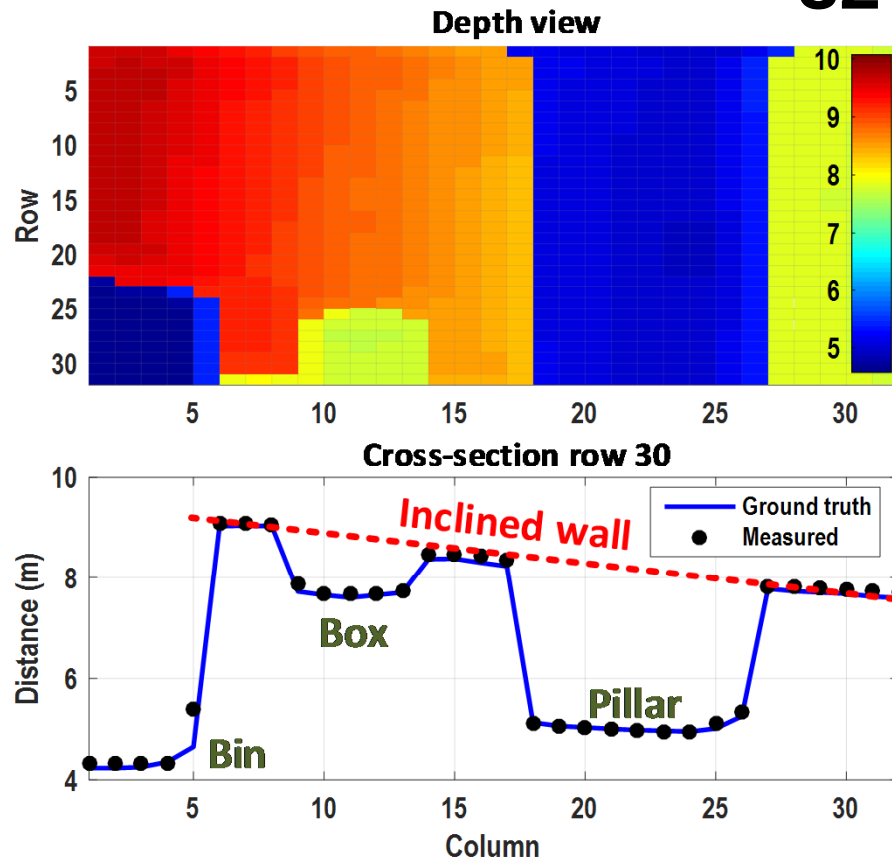
Scanner system



- 2-axis scanner
- Low-power laser
- Flexible lateral resolution

Scanner system

32 x 32



Different target reflectivities

- [1] – White wall – 50%
- [2] – Black wall – 8%
- [3] – White pillar – 60%
- [4] – Aluminum bin – 54%
- [5] – Cardboard box – 21%

Scanner system

256 x 256

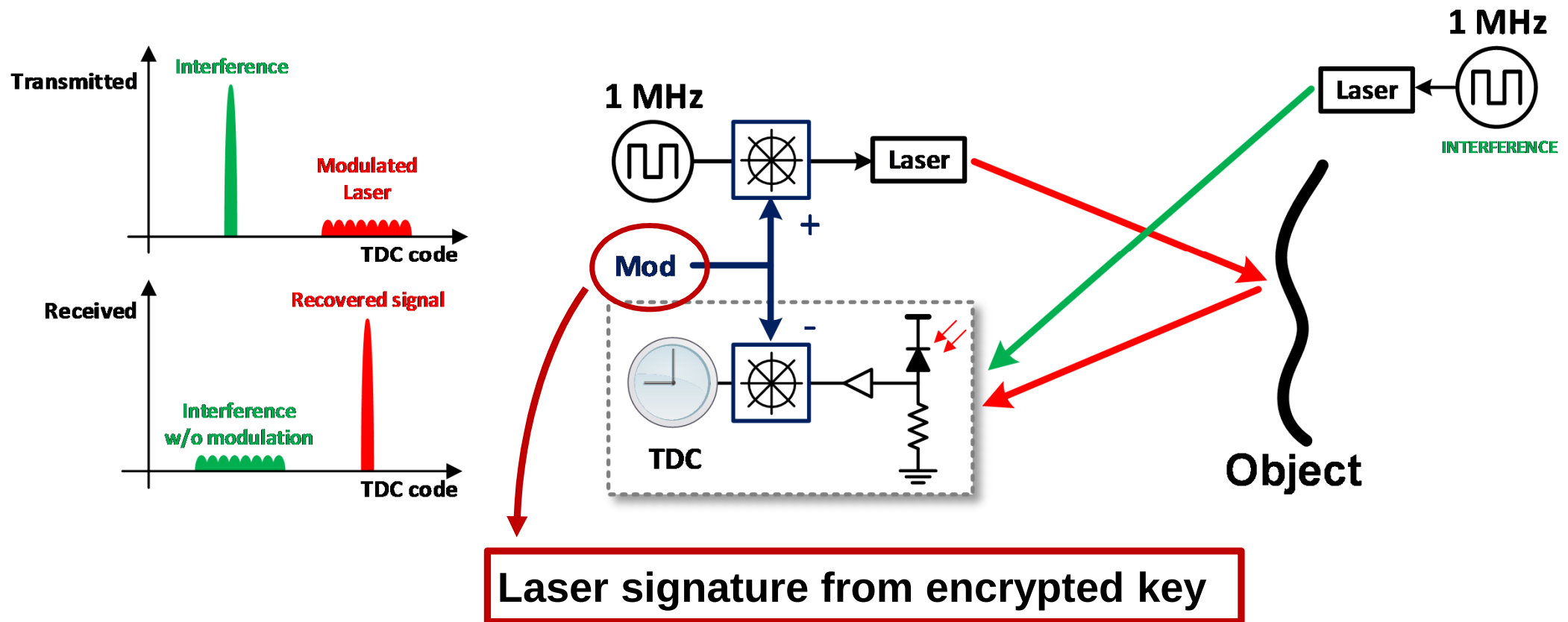
**Letters:
15mm tall**

**5ms exposure
per point**

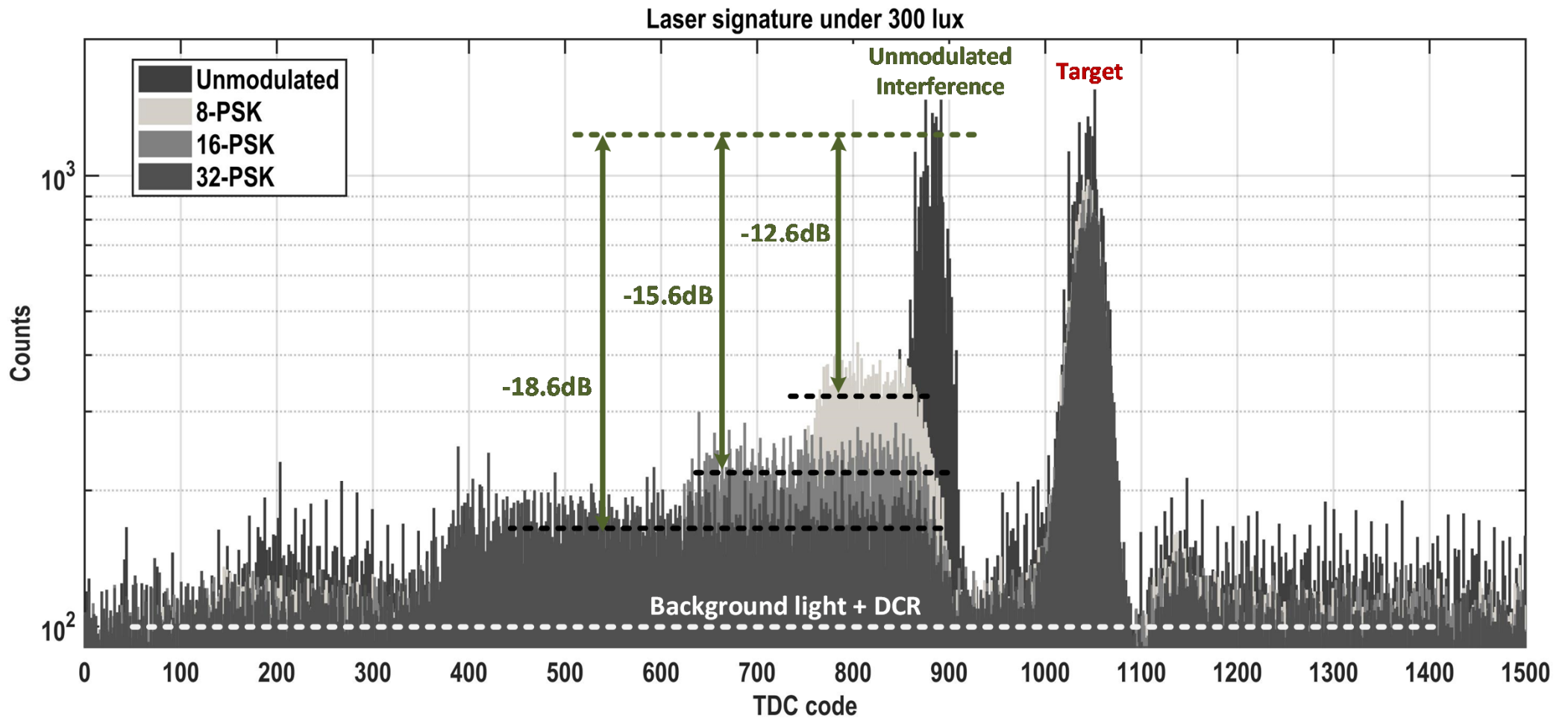
Measured at 4.5m



Interference suppression – Laser signature

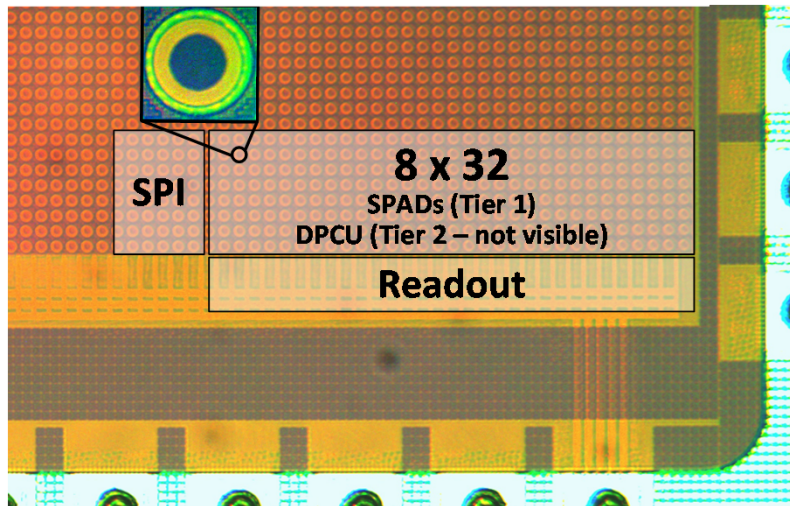


Interference suppression



Summary

- First 3D-stacked **dTOF** sensor
- **ROIC** digitally synthesized
- Longest single-point measurement in CMOS
- Proposed laser signature

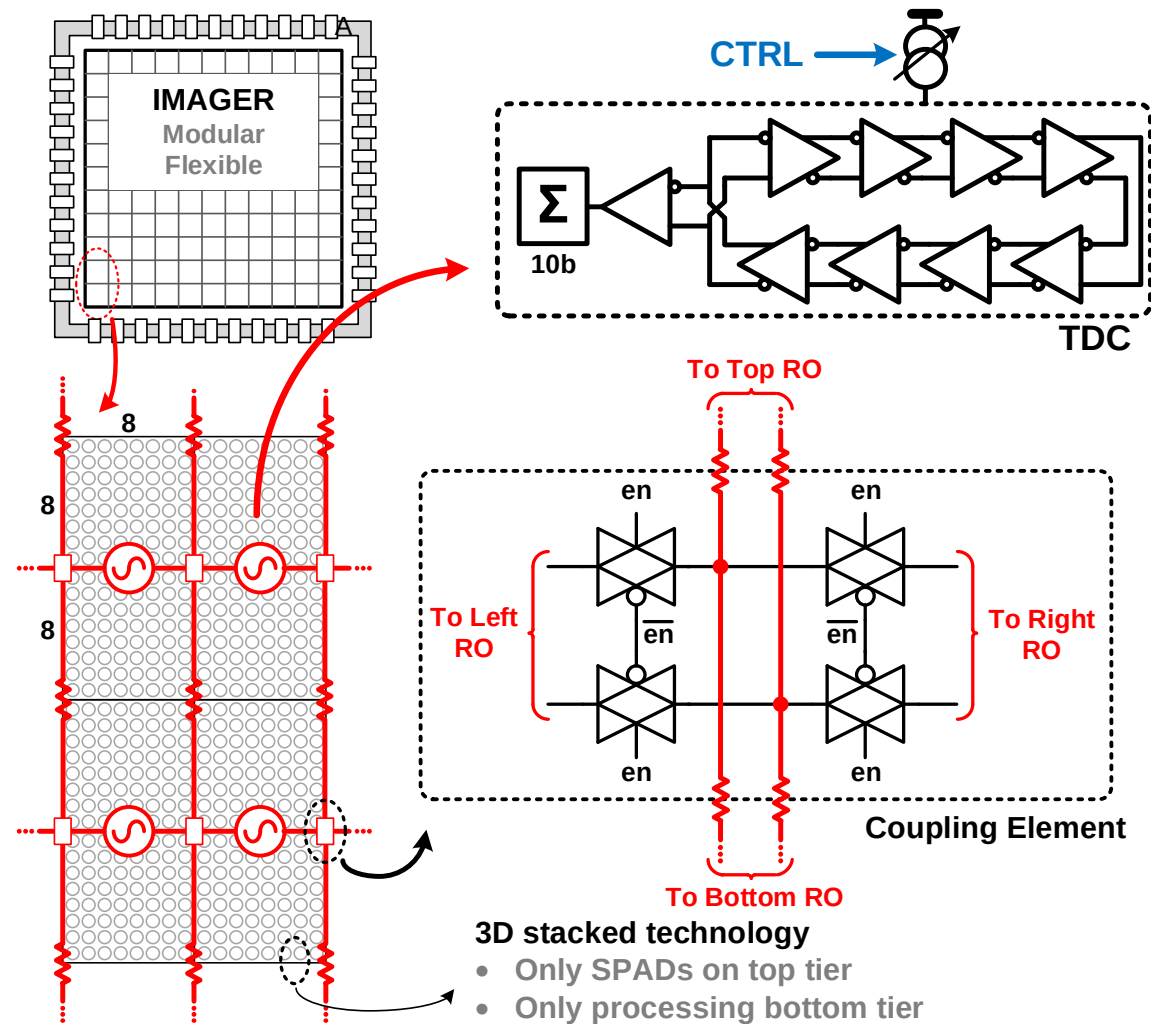


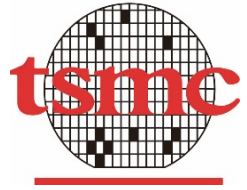
Parameter	Performance
Technology	45/65nm CMOS
Pixel pitch	19.8 μ m
Pixel fill factor	31.3/50.6%
SPAD median DCR	55.4 cps/ μ m ² @ 2.5V
TDC resolution	60 – 320ps
TDC power	0.5 – 0.1mW
TDC area	550μm²
Distance range	150 – 430m
Precision (σ) (Repeatability)	0.15 – 0.47m
	0.1 – 0.11%
Accuracy (Non-linearity)	0.07 – 0.8m
	0.3 – 0.4%

Timing

Timing reference

- Precise timing is essential
- Stable and well-known resolution
- Robust to PVT variations
- Low power and area





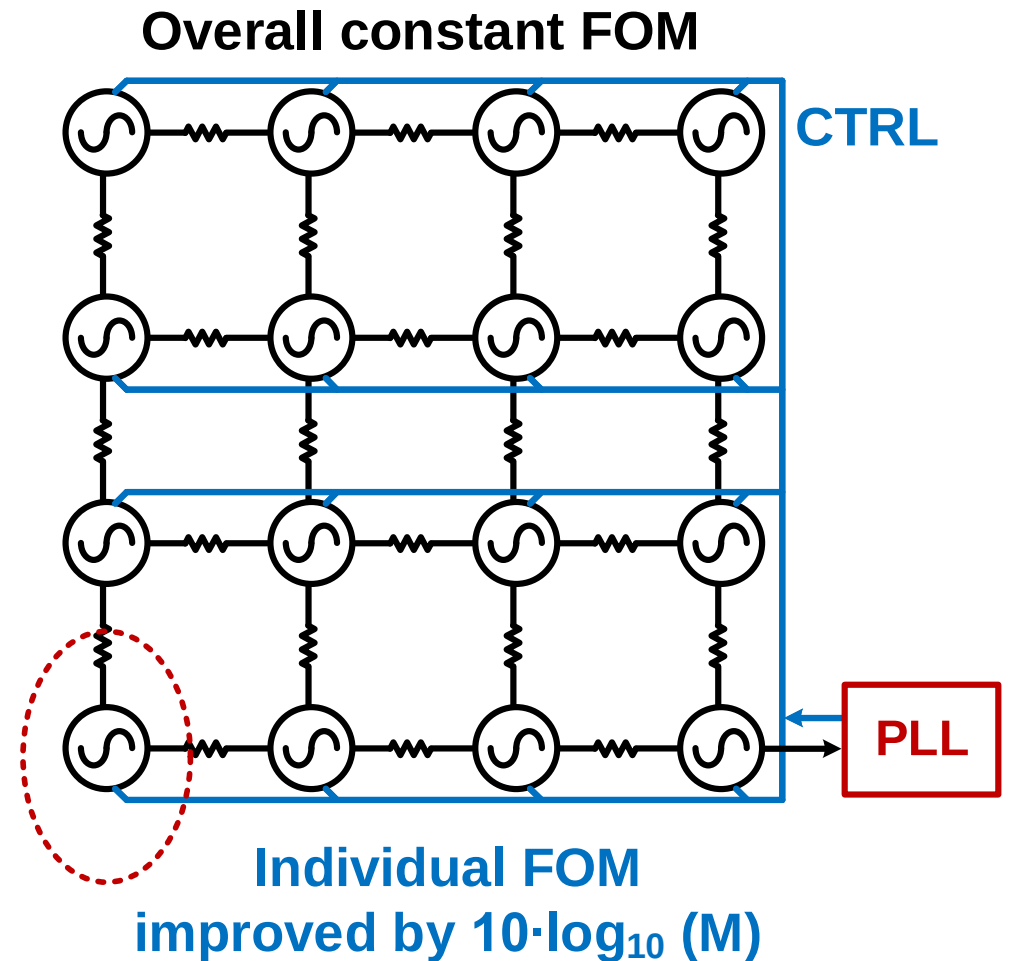
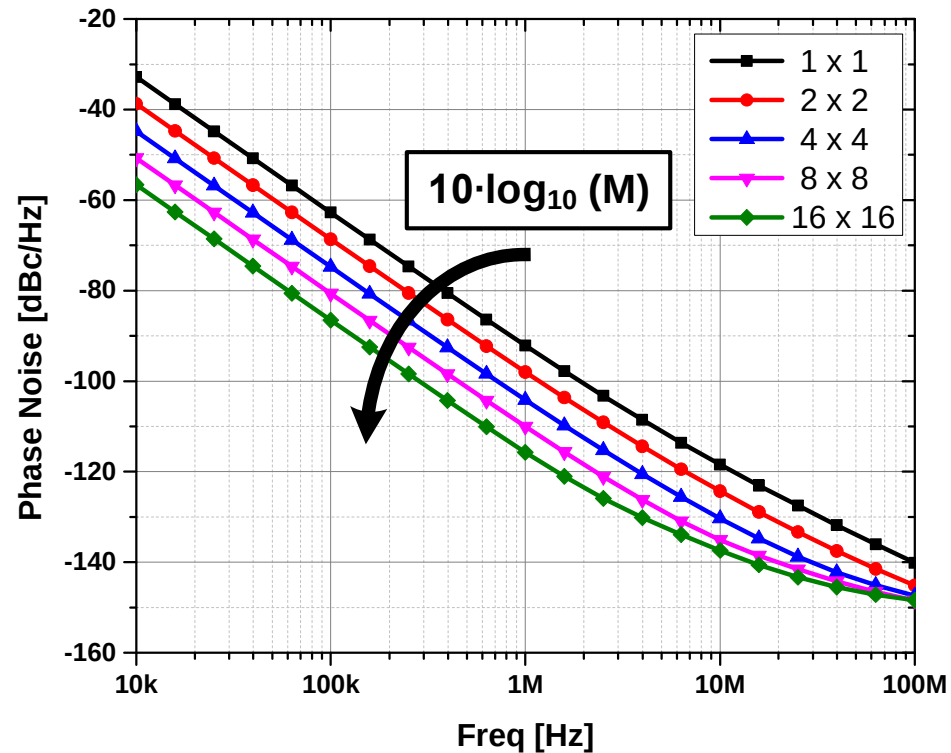
Timing in large sensors

IISW 2017: *Mutually Coupled Ring Oscillators for Large Array Time-of-Flight Imagers*

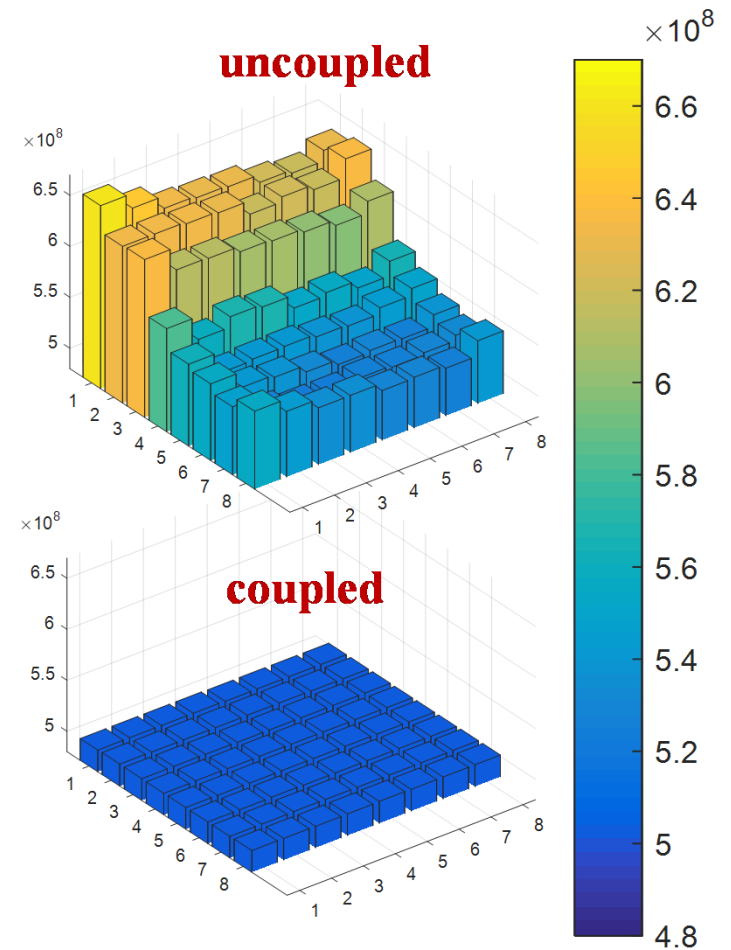
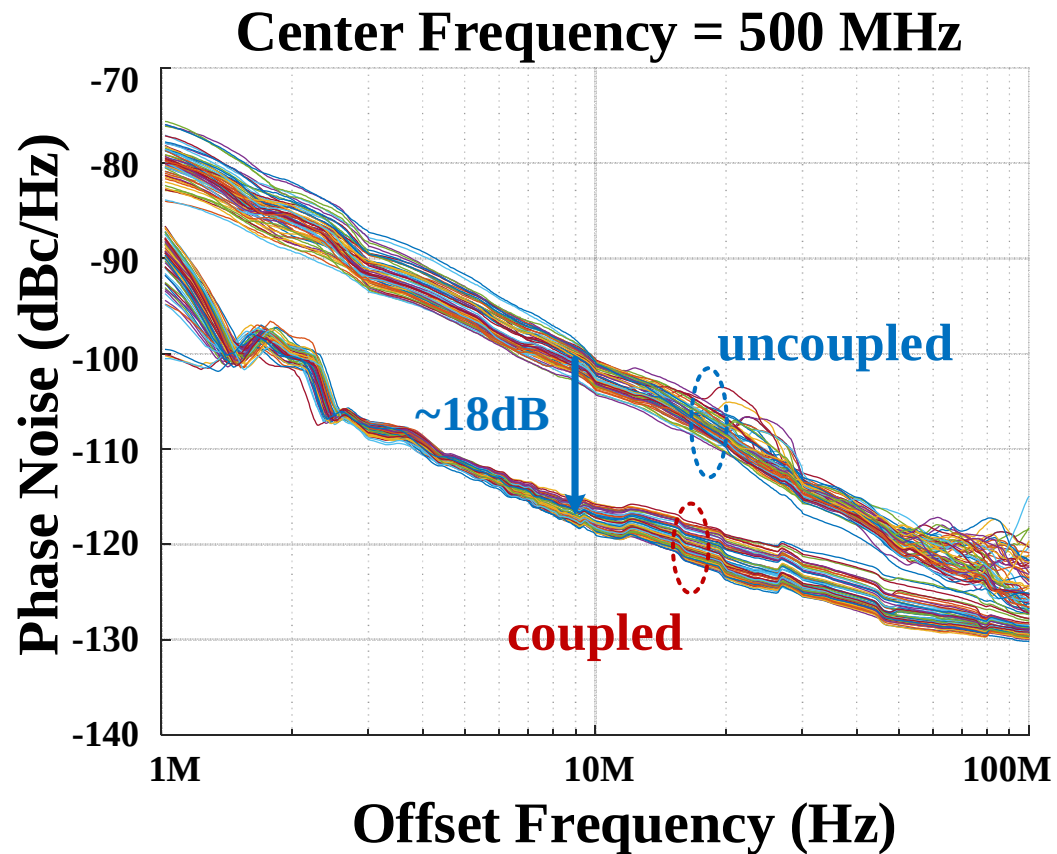
A. R. Ximenes¹, P. Padmanabhan², E. Charbon^{1,2}

High-quality timing

Phase noise simulation
FOM ~ 150 dB @ 500 MHz

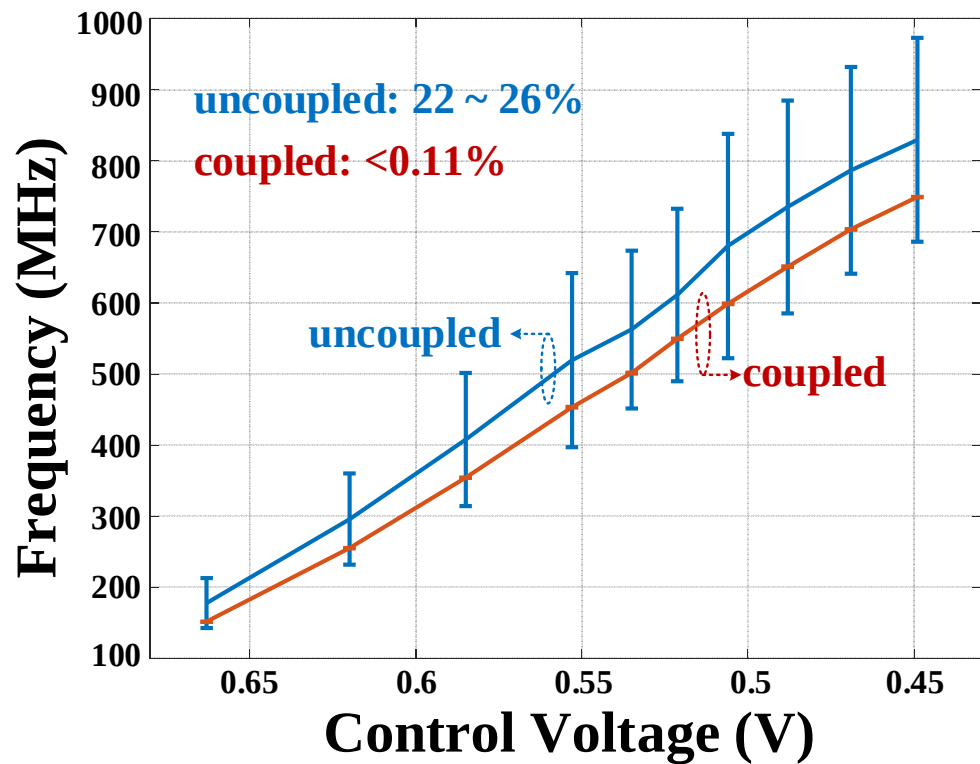


High-quality timing

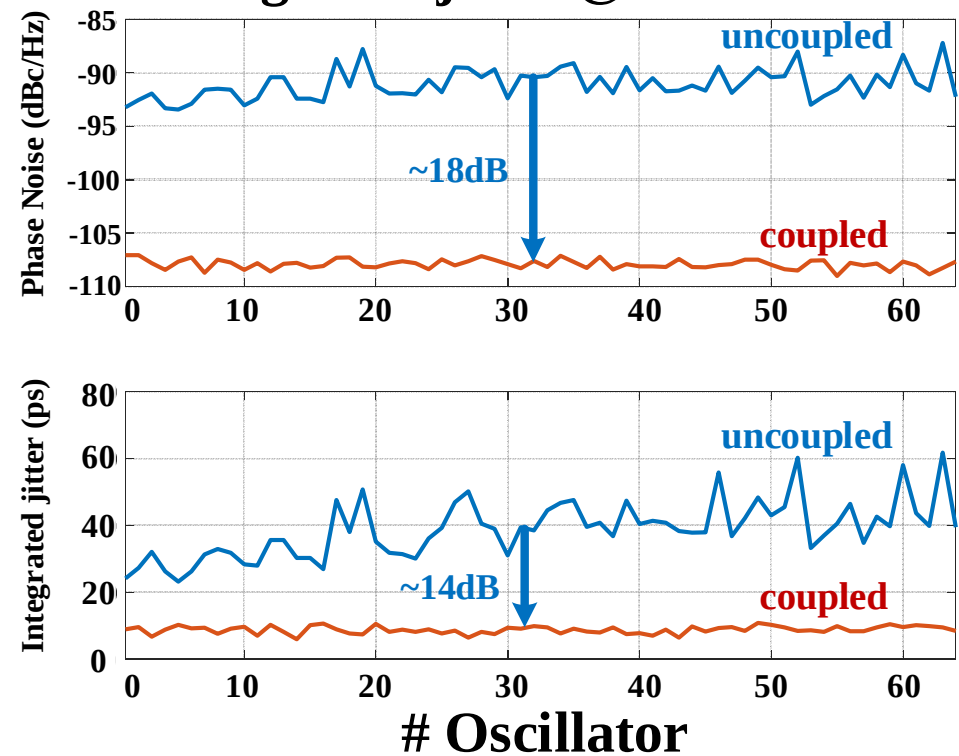


High-quality timing

Frequency variation



Phase noise (3 MHz) and integrated jitter @ 500MHz



Conclusion

- Reducing power consumption and data is essential
- Precise timing in large arrays challenging
- Future work
 - Implement both solutions in a large array

Thank you!

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